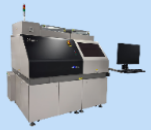
Post Dicing Quality

Purpose	High Performance Defect Metrology Solutions to ensure Post Dicing Quality of wafer level packages on Wafer frames, Waffle and JEDEC Trays.
Technology	1. **Inner Crack Using Optical Interference** – Using Optical Interference or Infrared capability 2. **Inner Crack Using Infrared –** Capabilities include Side Wall, Top and Bottom View Inspection 3. **Dicing Defect Metrology** – Field proven inspection algorithm to inspect Edge & Corner Defects, Active Die, Saw Street Quality, Die Alignment on Stretched wafer, Die Edge Micro Crack Inspection, Die Shift Inspection 4. **Side Wall Inspection –** Inspect Surface and Inner crack defects

STI Products	Inner Crack	Dicing Defect Metrology	Side Wall Inspection
 **iFocus – Wafer 2D & 3D Scan**	✓	✓	
 **tSort – WLP Scan & Sort**	✓	✓	✓
 **Hexa – Tray 2D & 3D Scan**	✓		✓
 **tScan – 2D & 3D High Speed Scan-Pack**	✓		✓